

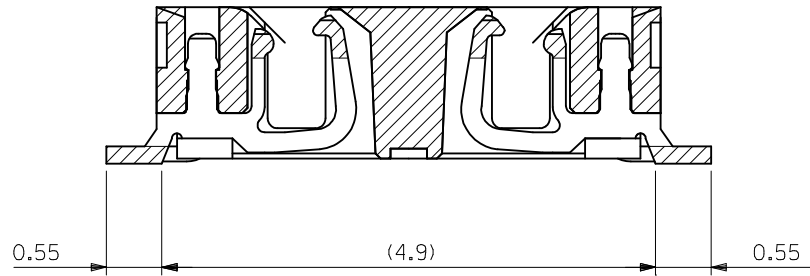
注記  
NOTES:

1. 材質  
MATERIAL  
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL 94V-0  
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL 94V-0  
ターミナル: 銅合金 (t=0.15)  
TERMINAL: COPPER ALLOY (t=0.15)  
ネイル: 銅合金 (t=0.2)  
NAIL: COPPER ALLOY (t=0.2)
2. メッキ仕様  
PLATING  
ターミナル  
TERMINAL  
接点部: 金メッキ 0.25マイクロメートル以上  
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM  
半田付け部: 金メッキ 0.4マイクロメートル以下  
SOLDER TAIL AREA: GOLD 0.4 MICROMETER MAXIMUM  
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上  
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM  
ネイル  
NAIL  
錫メッキ 3.0マイクロメートル以上  
TIN 3.0 MICROMETER MINIMUM  
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上  
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
3. テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた平坦度は、0.1ミリメートル以下。  
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
4. 嵌合相手: 55201-\*\*\*\*、55650-\*\*\*\* (H=2mm)  
MATED CONN.: 55201-\*\*\*\*, 55650-\*\*\*\* (H=2mm)
5. 本製品は、54363-\*\*71(エンボス梱包品 54363-\*\*78)のニッケルバリア品である。  
THIS PRODUCT IS 'NICKEL BARRIER' OF 54363-\*\*71(EMBOSSED TAPE PKG 54363-\*\*78).

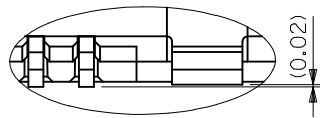
40.5	41.9	39.5	43.9	54363-1689	54363-1681	160	—
35.5	36.9	34.5	38.9	54363-1489	54363-1481	140	○
30.5	31.9	29.5	33.9	54363-1289	54363-1281	120	○
28	29.4	27	31.4	54363-1189	54363-1181	110	○
25.5	26.9	24.5	28.9	54363-1089	54363-1081	100	○
23	24.4	22	26.4	54363-0989	54363-0981	90	—
20.5	21.9	19.5	23.9	54363-0889	54363-0881	80	○
18	19.4	17	21.4	54363-0789	54363-0781	70	○
15.5	16.9	14.5	18.9	54363-0689	54363-0681	60	○
13	14.4	12	16.4	54363-0589	54363-0581	50	○
10.5	11.9	9.5	13.9	54363-0489	54363-0481	40	○
8	9.4	7	11.4	54363-0389	54363-0381	30	○
5.5	6.9	4.5	8.9	54363-0289	54363-0281	20	○
D	C	B	A	エンボス梱包品 EMBOSSED TAPE PACKAGING	製品番号 MATERIAL NO.	極数 CIRCUITS	量産対応 AVAILABLE

REVISED EC NO: J2016-0601 DRWN: JFURUKAWA 2015/12/08 CHKD: TASAKAWA 2015/12/08 APPR: KMORIKAWA 2015/12/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS		THIRD ANGLE PROJECTION  <b>0.5 MM PITCH B/B CONN. WITH FITTING NAIL -LEAD FREE-</b>  <b>molex</b>  SD-54363-050 SHEET NO. 1 OF 2
			MM ONLY		10:1	METRIC		
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	Y. AOYAGI	2006/11/08			
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE			
1.0 OVER	10 UNDER	±0.2	K. TOYODA	2006/11/08				
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE				
30 OVER		±0.3	N. UKITA	2006/11/08				
ANGULAR	±3 °		MATERIAL NO.		DOCUMENT NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

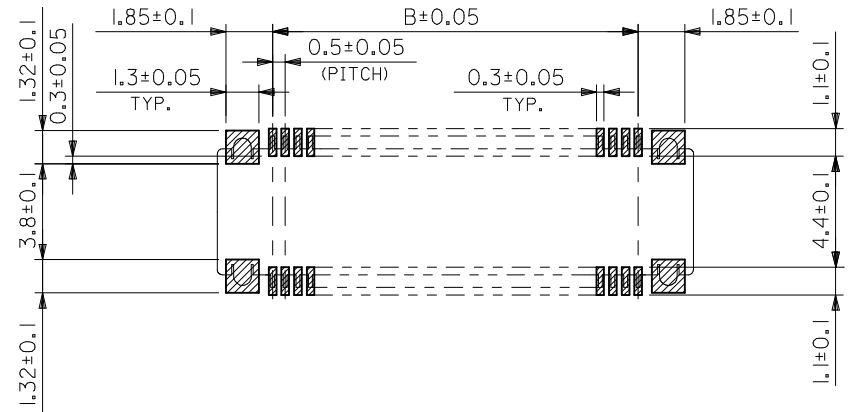
10 9 8 7 6 5 4 3 2 1



半田付け部詳細図  
DETAIL FOR SOLDERING AREA



上部詳細  
DETAIL T



推奨基板寸法  
RECOMMENDED PCB PATTERN LAYOUT  
(SCALE 5:1)

REVISED EC NO: J2016-0601 DRWN: JFURUKAWA 2015/12/08 CHKD: TASAKAWA 2015/12/08 APPR: KMORIKAWA 2015/12/16	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	Y. AOYAGI	2006/11/08	0.5 MM PITCH B/B CONN. WITH FITTING NAIL -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE			
	1.0 OVER	30 UNDER	±0.2	K. TOYODA	2006/11/08	molex		
	10 OVER	30 UNDER	±0.25	APPROVED BY	DATE			
30 OVER		±0.3	N. UKITA	2006/11/08	MATERIAL NO.		DOCUMENT NO.	
ANGULAR	±3 °		SEE SHEET 1		SD-54363-050		SHEET NO. 2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1